

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-22 (canceled).

Claim 23 (currently amended): ~~[[The]]~~ A method of claim 2 for fabricating a wiring substrate comprising the steps of:

forming an insulating film on a metal base having openings on the metal base at positions corresponding to metal bumps to be formed later;

forming at least one layer of wiring on the base made of a metal through the insulating film, the layer of wiring having a wiring film formed thereon by electroplating; and  
selectively etching the base,

wherein the wiring layer formed through the insulating film is in contact with the metal base.

Claim 24 (currently amended): The method of claim ~~[[2]]~~ 25, wherein the wiring layer formed through the insulating film is in ~~contact with the metal base at the openings in the~~

~~insulating film and in~~ contact with the insulating film where there are no openings in the insulating film.

Claim 25 (currently amended): The method of claim ~~[[2]]~~ 23, wherein the wiring layer is formed in the area of the openings on the insulating film ~~so as to be formed through the film in~~ contact with the base.

Claim 26 (canceled).

Claim 27 (currently amended): ~~[[The]]~~ A method of claim 2 for fabricating a wiring substrate comprising the steps of:  
forming an insulating film on a metal base having openings on the metal base at positions corresponding to metal bumps to be formed later;  
forming at least one layer of wiring on the base made of a metal through the insulating film, the layer of wiring having a wiring film formed thereon by electroplating; and  
selectively etching the base,  
wherein the wiring film ~~can function~~ functions as an etching stopper.